

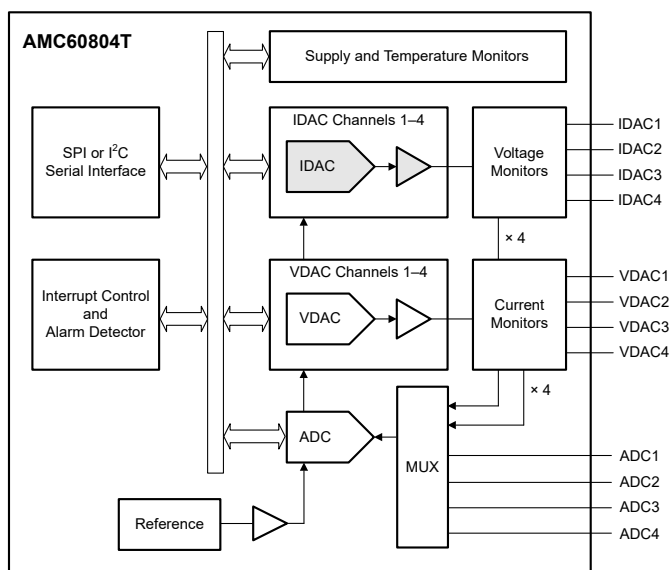
AMC60804T 具有电流和电压输出 DAC 和多通道 ADC 的 4 通道光学监视器和控制器

1 特性

- 四个 12 位电流输出 DAC (IDAC)
 - 200mA 满量程输出范围
 - 低电源余量：200 mV/200 mA
- 四个 12 位电压输出 DAC (VDAC)
 - 可选的满量程输出范围：
 - 5V、-2.5V、+2.5V 和 +5V
 - 高电流驱动能力：±50mA
- 多通道 12 位、1MSPS SAR ADC
 - 四个外部输入：电压范围为 2.5V 至 5V
 - 四个 IDAC 电压监测通道
 - 四个 VDAC 电流监测通道
 - 可编程序列发生器
 - 可编程超限报警
- 内部 2.5V 基准电压
- 电源和温度故障警报
- SPI 和 I²C 接口：1.7V 至 3.6V 工作电压
 - SPI：4 线接口
 - I²C：四个目标地址
- 额定温度范围：-40°C 至 +125°C

2 应用

- 光学模块
- 数据中心内部互联 (地铁)



简化原理图

3 说明

AMC60804T 是一款高度集成的低功耗模拟监视器和控制器，适用于光收发器应用。

AMC60804T 包括四个 12 位电流输出数模转换器 (IDAC) 和四个 12 位电压输出 DAC (VDAC)，具有可编程输出范围。该器件还包括一个用于内外部信号监测的 12 位 1MSPS 模数转换器 (ADC)、电源和温度警报监控器以及一个高精度内部基准。

AMC60804T VDACC 可在正负输出范围内运行，能够拉出和灌入高达 50mA 的电流，是偏置光学调制器的理想选择。此外，AMC60804T IDACC 支持 200mA 的满量程输出范围和超低功率耗散。IDACC 无需使用外部元件来偏置激光二极管。AMC60804T 将四个 VDACC 和四个 IDACC 集于一身，可实现电吸收调制激光器的精确偏置。

AMC60804T 还包含四个多路复用到 ADC 的输入引脚，以及一个低延迟窗口比较器。这些特性使该器件非常适用于接收信号强度指示器 (RSSI) 和信号丢失 (LOS) 检测。ADC 还能测量 IDACC 引脚的电压以及由 VDACC 拉出或灌入的电流，从而能够监控输出。

AMC60804T 的低功耗、高集成度、超小尺寸和宽工作温度范围特性使其非常适用于光模块一体化控制电路。

封装信息

器件型号	封装 ⁽¹⁾	封装尺寸 (标称值)
AMC60804T	YBH (DSBGA , 36)	2.56mm × 2.56mm

(1) 要了解所有可用封装，请参见数据表末尾的封装选项附录。



4 Device and Documentation Support

4.1 Documentation Support

备注

TI is transitioning to use more inclusive terminology. Some language may be different than what you would expect to see for certain technology areas.

4.1.1 Related Documentation

For related documentation, see the following: [AMC60304EVM user's guide](#)

4.2 Trademarks

所有商标均为其各自所有者的财产。

4.3 静电放电警告



静电放电 (ESD) 会损坏这个集成电路。德州仪器 (TI) 建议通过适当的预防措施处理所有集成电路。如果不遵守正确的处理和安装程序, 可能会损坏集成电路。

ESD 的损坏小至导致微小的性能降级, 大至整个器件故障。精密的集成电路可能更容易受到损坏, 这是因为非常细微的参数更改都可能会导致器件与其发布的规格不相符。

4.4 术语表

[TI 术语表](#) 本术语表列出并解释了术语、首字母缩略词和定义。

5 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
AMC60804TYBHR	ACTIVE	DSBGA	YBH	36	3000	RoHS & Green	SNAGCU	Level-1-260C-UNLIM	-40 to 125	AMC60804T	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSELETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

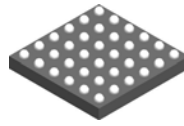
(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

Important Information and Disclaimer:The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

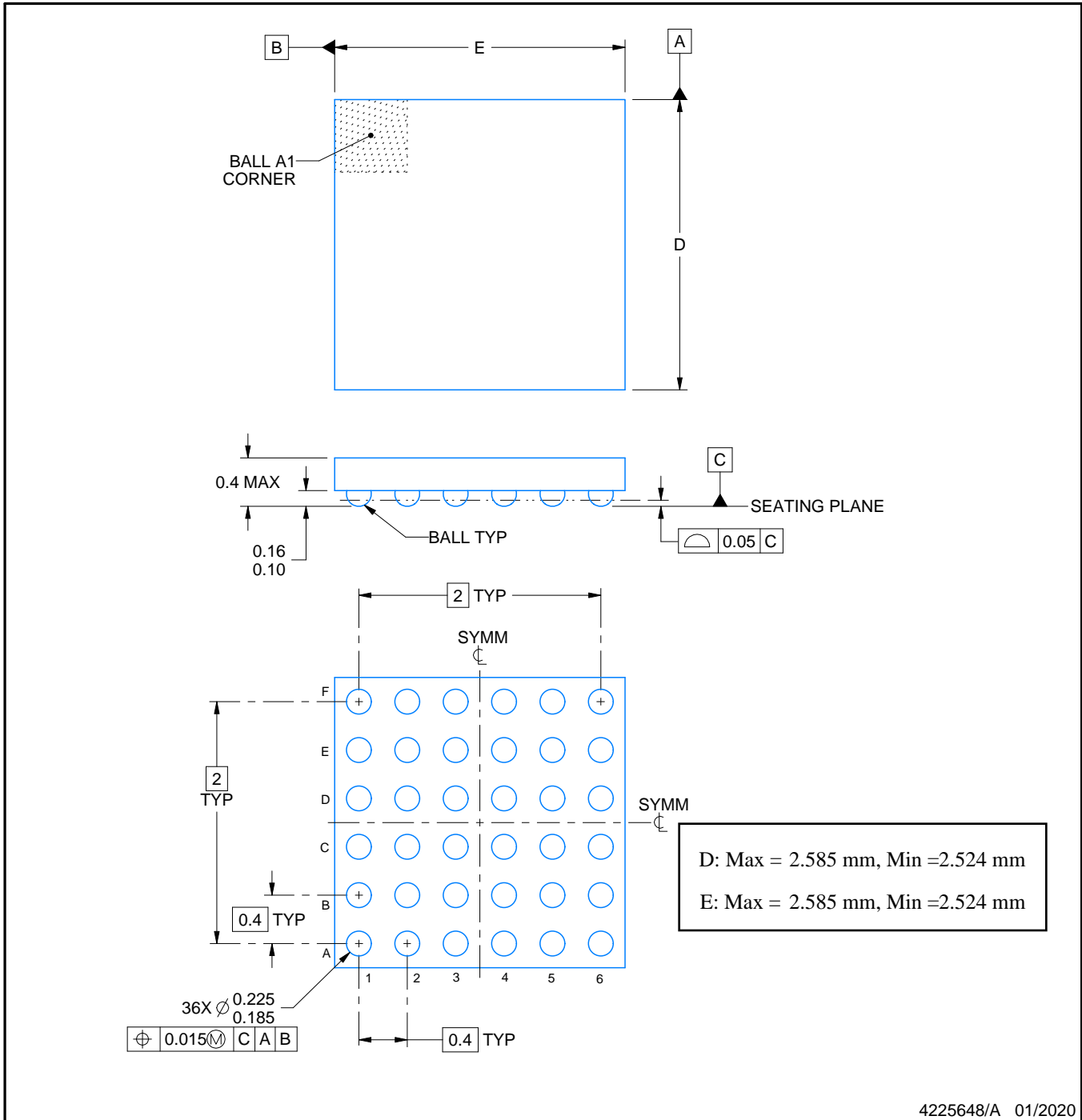
In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

YBH0036



PACKAGE OUTLINE
DSBGA - 0.4 mm max height

DIE SIZE BALL GRID ARRAY



NOTES:

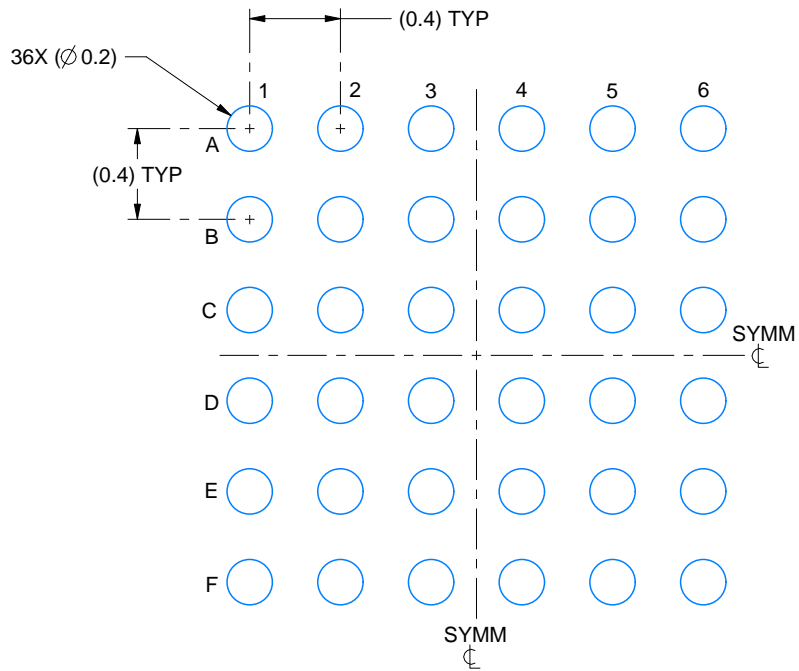
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.

EXAMPLE BOARD LAYOUT

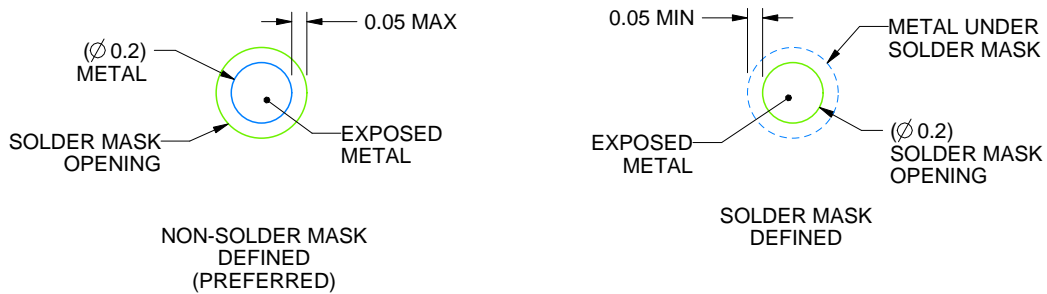
YBH0036

DSBGA - 0.4 mm max height

DIE SIZE BALL GRID ARRAY



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 30X



SOLDER MASK DETAILS
NOT TO SCALE

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NOTES: (continued)

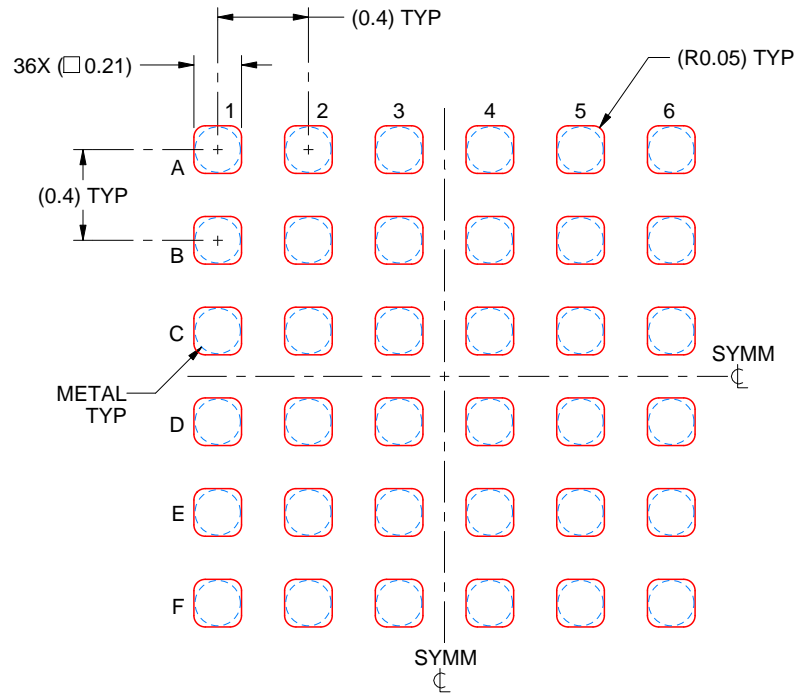
- Final dimensions may vary due to manufacturing tolerance considerations and also routing constraints. See Texas Instruments Literature No. SNVA009 (www.ti.com/lit/snva009).

EXAMPLE STENCIL DESIGN

YBH0036

DSBGA - 0.4 mm max height

DIE SIZE BALL GRID ARRAY



SOLDER PASTE EXAMPLE
BASED ON 0.075 mm THICK STENCIL
SCALE: 30X

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NOTES: (continued)

4. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release.

重要声明和免责声明

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